

Examiner Sikyin Ip  
October 14, 2007  
Page 2

APPLICATION NO. 10/666,129

PROPOSED CLAIM AMENDMENTS

Claims 1 - 12 (cancelled)

13. (currently amended) A lead-free solder alloy consisting of 0.1 - 3 1.5 wt% of Cu, 0.001 - 0.1 wt% of P, greater than 0 and at most 0.3 wt % of Ni, and a balance of Sn.

14. (previously presented) A lead-free solder alloy as claimed in claim 13 wherein the content of P is 0.001 - 0.05 wt%.

15. (previously presented) A lead-free solder alloy as claimed in claim 13 wherein the content of P is 0.001 - 0.01 wt%.

16. (previously presented) A solder paste comprising the lead-free solder alloy of claim 13.

17. (previously presented) A flow soldered joint connected to an electronic component and formed by flow soldering with a lead-free solder alloy as claimed in claim 13.

18. (previously presented) A soldering method comprising forming a bath of molten solder of the lead-free solder alloy as claimed in claim 13 and contacting an electronic component with

Examiner Sikylin Ip  
October 14, 2007  
Page 3

the molten solder.

11/88935-6

19. (previously presented) A method as claimed in claim 18 including contacting the electronic component with a wave of the molten solder.

Claims 20 - 31 (cancelled)

32. (previously presented) A flow soldered joint as claimed in claim 17 which connects the electronic component to a printed wiring board.

33. (previously presented) A method as claimed in claim 18 wherein the electronic component is disposed on a printed wiring board while contacting the molten solder.

Claims 34 - 36 (cancelled)

37. (previously presented) A lead-free solder alloy as claimed in claim 13 wherein the content of Cu is 0.3 - 1.5 wt%.

38. (previously presented) A lead-free solder alloy as claimed in claim 13 wherein the content of Cu is 0.4 - 1.0 wt%.

39. (previously presented) A lead-free solder alloy as

Examiner Sikyin Ip  
October 14, 2007  
Page 4

claimed in claim 37 wherein the content of P is 0.001 - 0.01 wt%.

Claims 40 - 41 (cancelled)

42. (new) A soldered joint comprising the solder alloy of claim 13.

43. (new) A soldering method comprising connecting an electronic component to another member using the solder alloy of claim 13.

44. (new) A soldering method comprising connecting an electronic component to another member using the solder paste of claim 16.